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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	68
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7064lc84-7

Email: info@E-XFL.COM

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- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
 - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
 - The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Table 3. MA	X 7000 S	peed Grad	les							
Device					Speed	Grade				
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		✓	✓		~		✓	✓	✓	
EPM7032S	✓	✓	✓		✓					
EPM7064		✓	✓		✓		✓	✓		
EPM7064S	✓	✓	✓		✓					
EPM7096			✓		✓		✓	✓		
EPM7128E			✓	✓	✓		✓	✓		✓
EPM7128S		✓	✓		✓			✓		
EPM7160E				✓	✓		✓	✓		✓
EPM7160S		✓	✓		✓			✓		
EPM7192E						✓	✓	✓		✓
EPM7192S			✓		✓			✓		
EPM7256E						✓	✓	✓		✓
EPM7256S			✓		✓			✓		

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

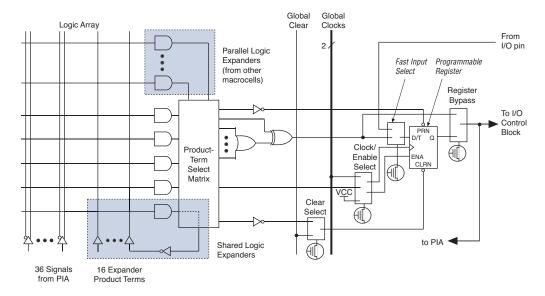
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



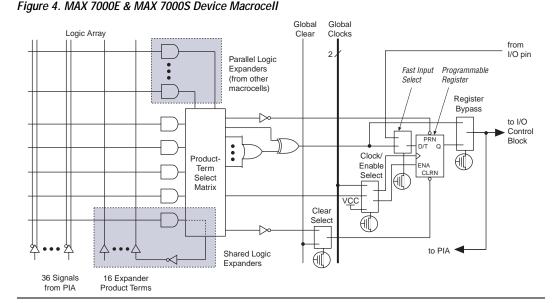


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

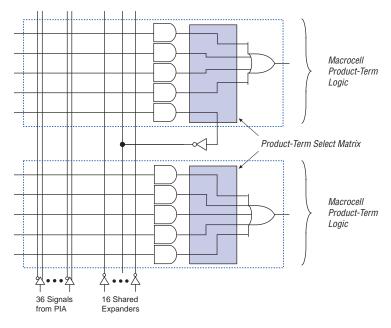
For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. Figure 5 shows how shareable expanders can feed multiple macrocells.

Figure 5. Shareable Expanders

Shareable expanders can be shared by any or all macrocells in an LAB.



Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where: t_{PROG} = Programming time

 t_{PPULSE} = Sum of the fixed times to erase, program, and

verify the EEPROM cells

Cycle_{PTCK} = Number of TCK cycles to program a device

 f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where: t_{VER} = Verify time

 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells

 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-Sca	n Register Length
Device	Boundary-Scan Register Length
EPM7032S	1 (1)
EPM7064S	1 (1)
EPM7128S	288
EPM7160S	312
EPM7192S	360
EPM7256S	480

Note:

(1) This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32	2-Bit MAX 7	000 Device IDCODE No	te (1)										
Device		IDCODE (32 Bits)											
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)									
EPM7032S	0000	0111 0000 0011 0010	00001101110	1									
EPM7064S	0000	0111 0000 0110 0100	00001101110	1									
EPM7128S	0000	0111 0001 0010 1000	00001101110	1									
EPM7160S	0000	0111 0001 0110 0000	00001101110	1									
EPM7192S	0000	0111 0001 1001 0010	00001101110	1									
EPM7256S	0000	0111 0010 0101 0110	00001101110	1									

Notes:

- (1) The most significant bit (MSB) is on the left.
- (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

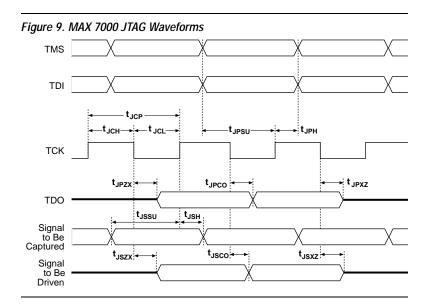


Figure 9 shows the timing requirements for the JTAG signals.

Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note 39 (IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices).*

Table 2	21. MAX 7000 & MAX 7000E Ext	ernal Timing Parame	eters Note	(1)					
Symbol	Parameter	Conditions	Speed Grade						
			MAX 700	0E (-10P)	MAX 70				
			Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns		
t _{SU}	Global clock setup time		7.0		8.0		ns		
t _H	Global clock hold time		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		5.0		5	ns		
t _{CH}	Global clock high time		4.0		4.0		ns		
t _{CL}	Global clock low time		4.0		4.0		ns		
t _{ASU}	Array clock setup time		2.0		3.0		ns		
t _{AH}	Array clock hold time		3.0		3.0		ns		
t _{ACO1}	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns		
t _{ACH}	Array clock high time		4.0		4.0		ns		
t _{ACL}	Array clock low time		4.0		4.0		ns		
t _{CPPW}	Minimum pulse width for clear and preset	(3)	4.0		4.0		ns		
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns		
t _{CNT}	Minimum global clock period			10.0		10.0	ns		
f _{CNT}	Maximum internal global clock frequency	(5)	100.0		100.0		MHz		
t _{ACNT}	Minimum array clock period			10.0		10.0	ns		
f _{ACNT}	Maximum internal array clock frequency	(5)	100.0		100.0		MHz		
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz		

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	00E (-10P)		00 (-10) 00E (-10)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t_{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t _{SU}	Register setup time		2.0		3.0		ns
t_H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t_{PIA}	PIA delay			1.0		1.0	ns
t_{LPA}	Low-power adder	(8)		11.0		11.0	ns

Table 2	26. MAX 7000 & MAX 7000E	Internal Timing P	aramete	rs No	ote (1)				
Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			2.0		2.0		3.0	ns
t _{IO}	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t _{FIN}	Fast input delay	(2)		2.0		_		4.0	ns
t _{SEXP}	Shared expander delay			8.0		10.0		9.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0		2.0	ns
t _{LAD}	Logic array delay			6.0		6.0		8.0	ns
t _{LAC}	Logic control array delay			6.0		6.0		8.0	ns
t _{IOE}	Internal output enable delay	(2)		3.0		_		4.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		5.0		-		6.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		8.0		-		9.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		7.0		-		11.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		-		14.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t _{SU}	Register setup time		4.0		4.0		4.0		ns
t _H	Register hold time		4.0		4.0		5.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.0		-		4.0		ns
t _{FH}	Register hold time of fast input	(2)	2.0		-		3.0		ns
t _{RD}	Register delay			1.0		1.0		1.0	ns
t _{COMB}	Combinatorial delay			1.0		1.0		1.0	ns
t _{IC}	Array clock delay			6.0		6.0		8.0	ns
t _{EN}	Register enable time			6.0		6.0		8.0	ns
t _{GLOB}	Global control delay			1.0		1.0		3.0	ns
t _{PRE}	Register preset time			4.0		4.0		4.0	ns
t _{CLR}	Register clear time			4.0		4.0		4.0	ns
t _{PIA}	PIA delay			2.0		2.0		3.0	ns
t _{LPA}	Low-power adder	(8)		13.0		15.0		15.0	ns

Table 2	9. EPM7064S External Timi	ing Parameters	(Part 2	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade	!			Unit
			-	5	-	6	-	7	-1		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 3	0. EPM7064S Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade	!			Unit
			-	-5 -6 -7 -10		-7		-10			
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t_{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t_{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t_{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t_{IOE}	Internal output enable delay			0.7		8.0		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		8.0		2.5		2.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t_{SU}	Register setup time		8.0		1.0		3.0		2.0		ns
t_H	Register hold time		1.7		2.0		2.0		3.0		ns

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 3	1. EPM7128S External Timi	ng Parameters	. No	te (1)								
Symbol	Parameter	Conditions	Speed Grade									
			-6		-	7	-1	10	-1	15		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns	
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns	
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz	
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns	
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz	
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz	

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade									
			-6		-	7	-1	10	-1	15		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{SU}	Global clock setup time		3.4		4.2		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns	
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		0.9		1.1		2.0		4.0		ns	
t _{AH}	Array clock hold time		1.7		2.1		3.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			6.7		8.2		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz	

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								Unit
			-	-6 -7			-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

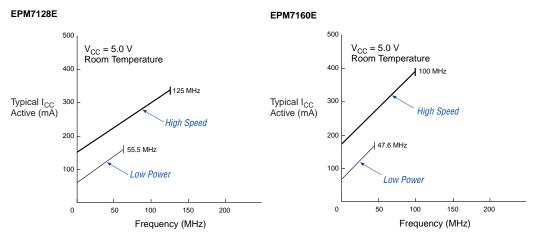
Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								Unit
			-	6	-7		-10		-15		-
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t _{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t _{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t _{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t _{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t_H	Register hold time		1.6		2.0		3.0		4.0		ns
t _{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t _{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t _{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t _{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t _{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t _{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t _{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns
t _{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns

Table 36. EPM7192S Internal Timing Parameters (Part 2 of 2) Note (1)										
Symbol	Parameter	Conditions		Speed Grade						
			-7		-10		-15		-	
			Min	Max	Min	Max	Min	Max		
t _H	Register hold time		1.7		3.0		4.0		ns	
t _{FSU}	Register setup time of fast input		2.3		3.0		2.0		ns	
t _{FH}	Register hold time of fast input		0.7		0.5		1.0		ns	
t _{RD}	Register delay			1.4		2.0		1.0	ns	
t _{COMB}	Combinatorial delay			1.2		2.0		1.0	ns	
t _{IC}	Array clock delay			3.2		5.0		6.0	ns	
t _{EN}	Register enable time			3.1		5.0		6.0	ns	
t _{GLOB}	Global control delay			2.5		1.0		1.0	ns	
t _{PRE}	Register preset time			2.7		3.0		4.0	ns	
t _{CLR}	Register clear time			2.7		3.0		4.0	ns	
t _{PIA}	PIA delay	(7)		2.4		1.0		2.0	ns	
t_{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns	

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 2 of 2)



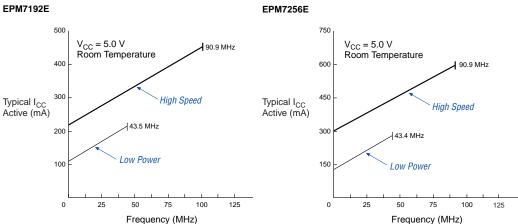
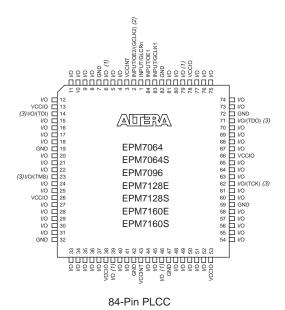


Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

Figure 19. 100-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

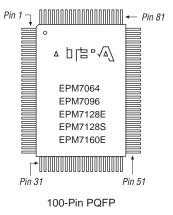


Figure 20. 160-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

